



Back to search results

Solder Anchor Attachment Method

Part Number: 374224B60023G

RoHS
 Compliant

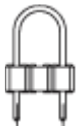
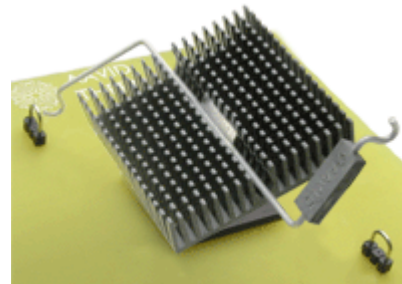


This part is in stock and available for immediate delivery

BGA Surface	Interface	Heat Sink Finish
All	T766	Black Anodize

Features and Benefits

- New unique wire clip design allows for complete reworkability after assembly
- Configurations are available for a wide range of BGA package sizes
- Minimal PC Board real estate is required for mounting
- Solder Anchors provide the most rugged mounting in the industry
- Each Heat Sink utilizes a phase change pad as the interface for optimal performance



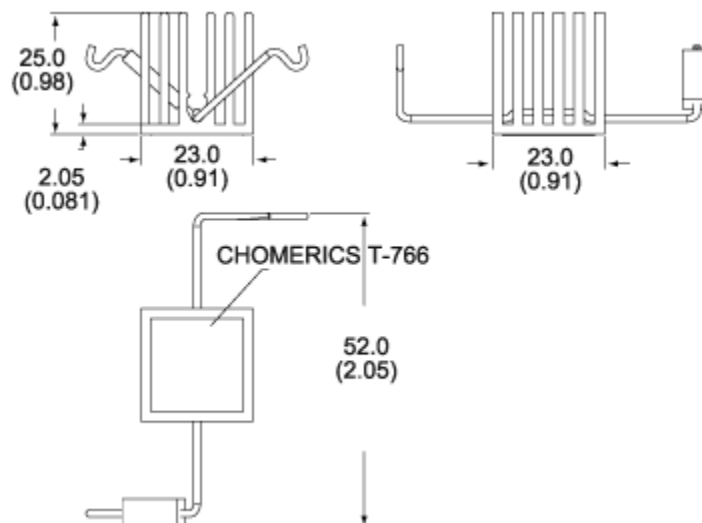
Solder anchors are sold separately

Part #	PCB Thickness
125700D00000G	0.063mm
125800D00000G	0.100-0.110 inches

2 Solder anchors must be soldered to the PCB Prior to attaching the heat sink clip.

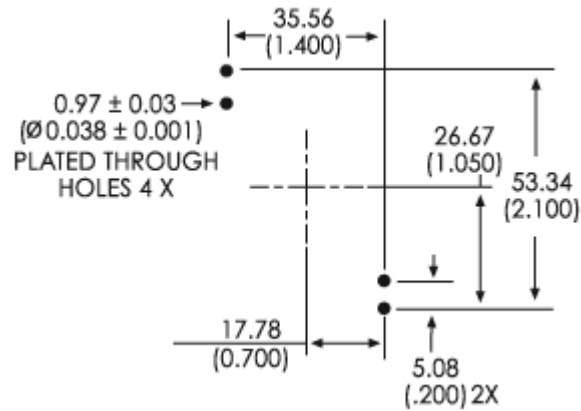
Width	Length	Height	Fin Thickness Across Width	Fin Thickness Across Length	Base Thickness	# of fins across width	# of fins across length
23mm	23mm	25mm	1.80mm	2.09mm	2.05mm	6	6

Mechanical Outline Drawing



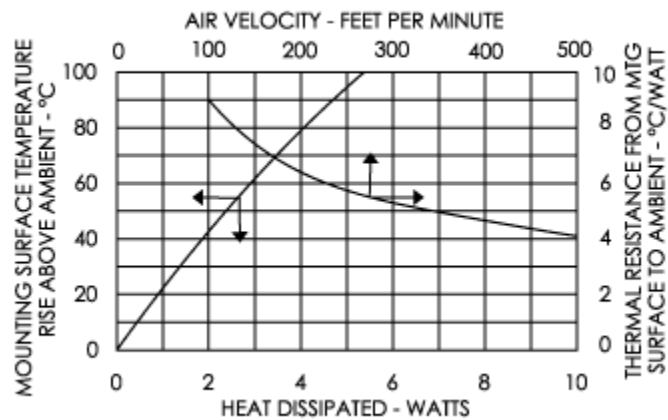
Unless otherwise shown, tolerances are $\pm 0.38(\pm 0.015)$

Recommended PCB Hole Pattern



Thermal Performance

* θ_n	** θ_f
19.7	6.37



*Natural convection thermal resistance is based on a 75 °C heat sink temperature rise.

**Forced convection thermal resistance based on an entering 1.0 m/s (200 lfm) airflow.
Due to various heat dissipation paths within a BGA device, please test the heat sink in your application.

This data sheet represents only one of a broad range of products we make to cool electronics.
Our representatives can help you configure a complete cooling solution for your individual applications.

• ©2011 Aavid Thermalloy, LLC